

Mendez, Gore Win for Apex Best Paper

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Friday, 04 April 2008 09:43 - Last Updated Friday, 04 April 2008 10:40

BANNOCKBURN, IL – Ramon Mendez and Brandon Gore won top honors for their papers at Apex this week, beating out more than 100 other paper submissions.

Mendez, a process development engineer at **Celestica**, and coauthors Mario Moreno, German Soto, Jessica Herrera and Craig Hamilton, won the International Best Paper for “Design for Manufacturability in Lead Free Wave Solder Process.”

Brandon Gore, signal integrity engineer at **Intel**, and coauthor Martyn Gaudion of **Polar Instruments**, won the US Best Paper award for “Toward a PCB Production Floor Metric for Go/No-Go Testing of Lossy High Speed Transmission Lines.”

Honorable Mention for International papers went to Bev Christian, director of the Materials Interconnect Research Group at **Research In Motion**, and coauthors Alexandre Romanov and Cameron O’Neil, for “Ionic Analysis of Common Beverages Spilled on Electronics.”

US Honorable Mention awards went to Dr. Ning-Cheng Lee, vice president of technology at **Indium**

, Dr. Benlih Huang and Dr. Hong-Sik Hwang for “A Compliant and Creep Resistant SAC-AI (Ni) Alloy.” And Aaron Unterborn, senior engineering manager at

Flextronics

, and coauthors Ken Wilson and Charles Merz shared an Honorable Mention for “Methods for Choosing a Saponifier or Surfactant for Printed Circuit Board and Stencil Cleaning Applications.”

Papers were evaluated for technical content, originality, test procedures and data used to deduce conclusions, quality of illustrations and the clarity and professionalism of writing.